



Product Change Notification

Change Notification #: 114085 - 00
Change Title: Intel® JBOD System JBOD2312S3SP
PCN 114085-00, Product Design,
Firmware Update - PSoC Version Upgrade to
1.12 on HSBP
Date of Publication: September 21, 2015

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material *:	Effective Immediately
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** Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.*

Description of Change to the Customer:

Intel is implementing the following changes on the hot swap backplane for the Intel® JBOD2312S3SP

1. Upgrade the firmware version for the PSoC on the HSBP from v1.10 to v1.12.
This change is being implemented in the WildCat Pass system in order to improve system test since now the BMC has PSoC V1.12 embedded in it.

The JBOD2312S3SP uses the same HSBP so this change will affect this product as well.

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers, but encourages customers to understand the changes and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
JBOD2312S3SP	939205	H54802-003	G97164-351	H54802-004	G97164-352

PCN Revision History:

Date of Revision: September 21, 2015	Revision Number: 00	Reason: Originally Published PCN
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to deviate from published specifications. Current characterized errata are available on request.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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